

PIC plating

Reflow Sn plating for low insertion/removal force

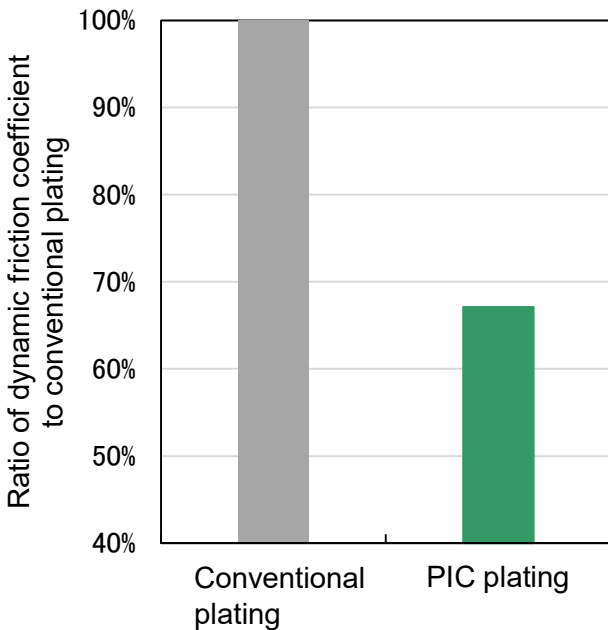
1. Features

- Low insertion/removal force of connectors, dynamic friction coefficient is up to around 30% lower than conventional reflow Sn plating (Conventional plating).
- Large amounts of Tin (Sn) are left between Cu-Sn intermetallic compound (IMC), achieving excellent electrical connection reliability.
- Available for various copper and copper alloys, such as Cu-Mg-based copper alloy, MSP series.

2. Application examples

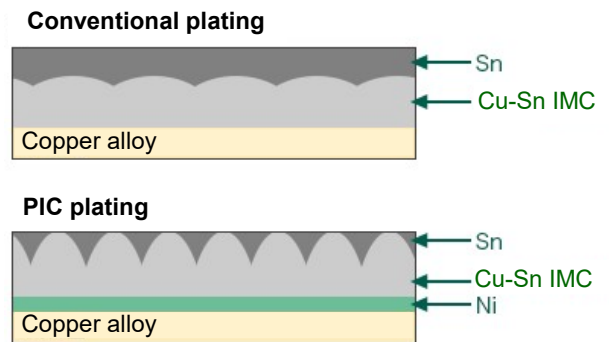
- Small terminals for automotive multipole connectors

4. Dynamic friction coefficient

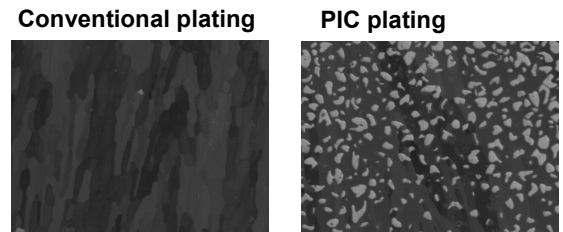


3. Structure of plating

- Cu-Sn IMC is precisely controlled to form columnar grains exposed homogeneously to the surface.
- Large amounts of Sn are left between Cu-Sn IMC grains.



Cross sections of plating



The white parts are Cu-Sn IMC.

Surface images of plating

5. Contact resistance

